



Information

Transfer of research and development business for semiconductor wafer bonding technology

October 31, 2025

TOKYO - Nikon Corporation (Nikon) announced that it has entered into a transfer agreement with SCREEN Holdings Co., Ltd. (SCREEN) regarding Nikon's research and development business for semiconductor wafer bonding technology as follows.

Background of the transfer

Wafer bonding is a technology that is attracting attention as a way to improve semiconductor performance. SCREEN and Nikon have been discussing future collaborations regarding this technology. As a result, Nikon has concluded that transferring the technology to SCREEN is the best option, leading to the signing of this agreement. Nikon and SCREEN will continue to strengthen our collaboration, aiming to further refine the technology and quickly implement it in actual semiconductor manufacturing.

Transfer details

Nikon's semiconductor wafer bonding technology, know-how, intellectual property, etc.

Overview of the transferee

Company name	SCREEN Holdings Co., Ltd.
Head office location	Tenjinkita-machi 1-1, Teranouchi-agaru 4-chome, Horikawa-dori, Kamigyo-ku, Kyoto, Japan
Representative	Masato Goto, President and Chief Executive Officer (CEO)
Capitalization	54.0 billion yen (As of March 31, 2025)
Date of establishment	October 11, 1943